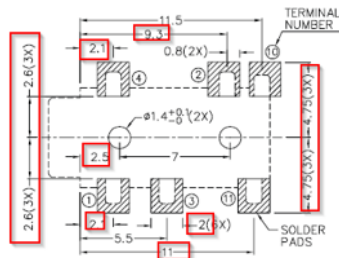




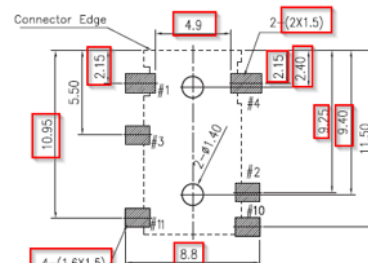
## 2. PCB Layout differs

PREVIOUS CUI DEVICES DETAIL / IMAGE



Recommended PCB Layout  
Top View

NEW CUI DEVICES DETAIL / IMAGE



Recommended PCB Layout  
Top View

## 3. Housing material differs

PREVIOUS CUI DEVICES DETAIL / IMAGE

	MATERIAL	PLATING
terminal 1	copper alloy	silver
terminal 2	copper alloy	silver
terminal 3	copper alloy	silver
terminal 4	copper alloy	silver
terminal 10	brass	silver
terminal 11	brass	silver
plastic	PA10T	

NEW CUI DEVICES DETAIL / IMAGE

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	phosphor bronze t-0.20	silver over nickel
terminal 2	phosphor bronze t-0.20	silver over nickel
terminal 3	phosphor bronze t-0.20	silver over nickel
terminal 4	phosphor bronze t-0.20	silver over nickel
terminal 10	brass t-0.20	silver over nickel
terminal 11	brass t-0.20	silver over nickel
housing	PA9T [UL94V-0]	black

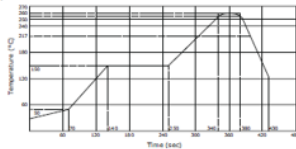
## 4. Reflow Soldering Difference

PREVIOUS CUI DEVICES DETAIL / IMAGE

### SOLDERABILITY

parameter	conditions/description	min	typ	max	units
refl storage	at relative humidity <80%		40		°C
reflow soldering <sup>1</sup>	see reflow profile	235	260	265	°C
drying conditions <sup>2</sup>	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

Notes: 3. Must reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <60%.  
4. When exceeding four lifts by >72 hours.



NEW CUI DEVICES DETAIL / IMAGE

### SOLDERABILITY

parameter	conditions/description	min	typ	max	units
refl storage	5-25°C, 20-75% humidity		40		°C
reflow soldering	see reflow profile	235	260	265	°C

Note: 1. CUI Devices recommends usage of the product within 24 hours after 100 is opened. After 24 hours, CUI Devices recommends drying the parts prior to use.

